

| Ref # | Hits    | Search Query   | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|---------|--|---|------------------|---------|------------------|
| L1    | 3504985 | (die chip ic (integrated adj circuit)<br>semiconductor flipchip (flip adj chip)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/17 21:10 |
| L2    | 41197   | (electrode terminal pad) with (embed<br>embedded embedding)                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/17 21:11 |
| L3    | 7464    | 1 same 2   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/17 21:12 |
| L4    | 121     | 3 same ((electro electrooptical)<br>(electro adj3 optical))                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/04/17 21:13 |